



**BOARD LEVEL COOLING – 10-6327**

10-6327 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. This heat sink is mounted with nylon push pins with springs. Representative image only.

**ORDERING INFORMATION**

Part Number	Device Type
10-6327-01G	BGA, FPGA

**HEAT SINK DETAILS**

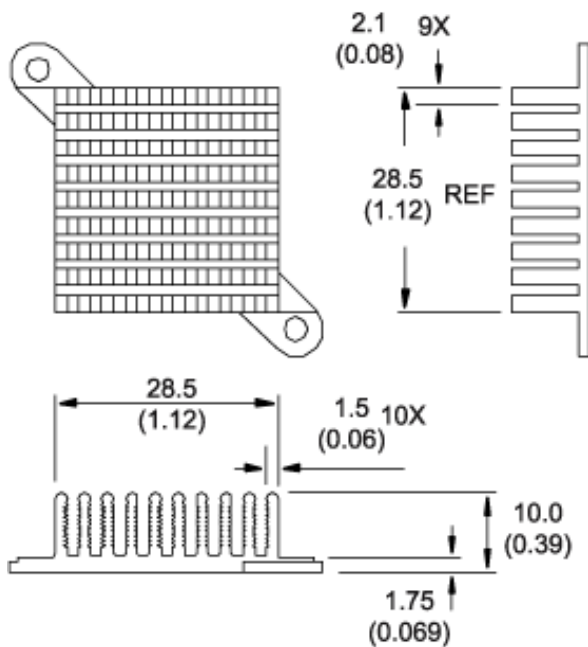
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Push Pin
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	28.50
Heat Sink Length (mm)	28.50
Heat Sink Height (mm)	10.00
Heat Sink Mounting Direction	Horizontal, Vertical



**MECHANICAL & PERFORMANCE**

Drawing dimensions are shown in mm, (in)



Mounting Details:

